

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT3350462

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Pin-Hong Chen	05/06/2015
Kuo-Chih Lai	05/06/2015
Chia Chang Hsu	05/06/2015
Chun-Chieh Chiu	05/06/2015
Li-Han Chen	05/06/2015
Shu Min Huang	05/06/2015
Min-Chuan Tsai	05/06/2015
Hsin-Fu Huang	05/06/2015
Chi-Mao Hsu	05/06/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	UNITED MICROELECTRONICS CORP.
<b>Street Address:</b>	No.3, Li-Hsin Road 2, Science-Based Industrial Park
<b>City:</b>	Hsin-Chu City
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14710583
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	3027291562
<b>Email:</b>	Patent.admin.uspto.cr@naipo.com
<b>Correspondent Name:</b>	WINSTON HSU
<b>Address Line 1:</b>	P.O.BOX 506
<b>Address Line 4:</b>	MERRIFIELD, VIRGINIA 22116
<b>ATTORNEY DOCKET NUMBER:</b>	NAUP2480USA
<b>NAME OF SUBMITTER:</b>	KATE YEH
<b>SIGNATURE:</b>	/KATE YEH/

**DATE SIGNED:**

05/12/2015

**Total Attachments: 18**

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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

**Title of Invention:**

**SEMICONDUCTOR STRUCTURE AND PROCESS FOR FORMING PLUG**

As the below named inventor, I hereby declare that:  
This declaration is directed to:

- The attached application, or
- United States application number \_\_\_\_\_ filed on \_\_\_\_\_, or
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The above-identified application was made or authorized to be made by me.

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I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

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representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WINTNESS WHEREOF, I have hereunto set hand and seal this     MAY 06 2015     (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Pin-Hong Chen**

Date: **MAY 06 2015**

Signature: Pin-Hong Chen

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Kuo-Chih Lai**

Date: **MAY 06 2015**

Signature: Lai - Kuo-chih

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chia Chang Hsu**

Date: **MAY 06 2015**

Signature: Chia Chang Hsu



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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chun-Chieh Chiu**

Date: **MAY 06 2015**

Signature: Chun-Chieh Chiu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Li-Han Chen**

Date: **MAY 06 2015**

Signature: Li-Han Chen

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shu Min Huang**

Date: **MAY 06 2015**

Signature: Shu Min Huang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Min-Chuan Tsai**

Date: **MAY 06 2015**

Signature: Min Chuan TSai



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Signature: Hsin Fu Huang

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Inventor: **Chi-Mao Hsu**

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